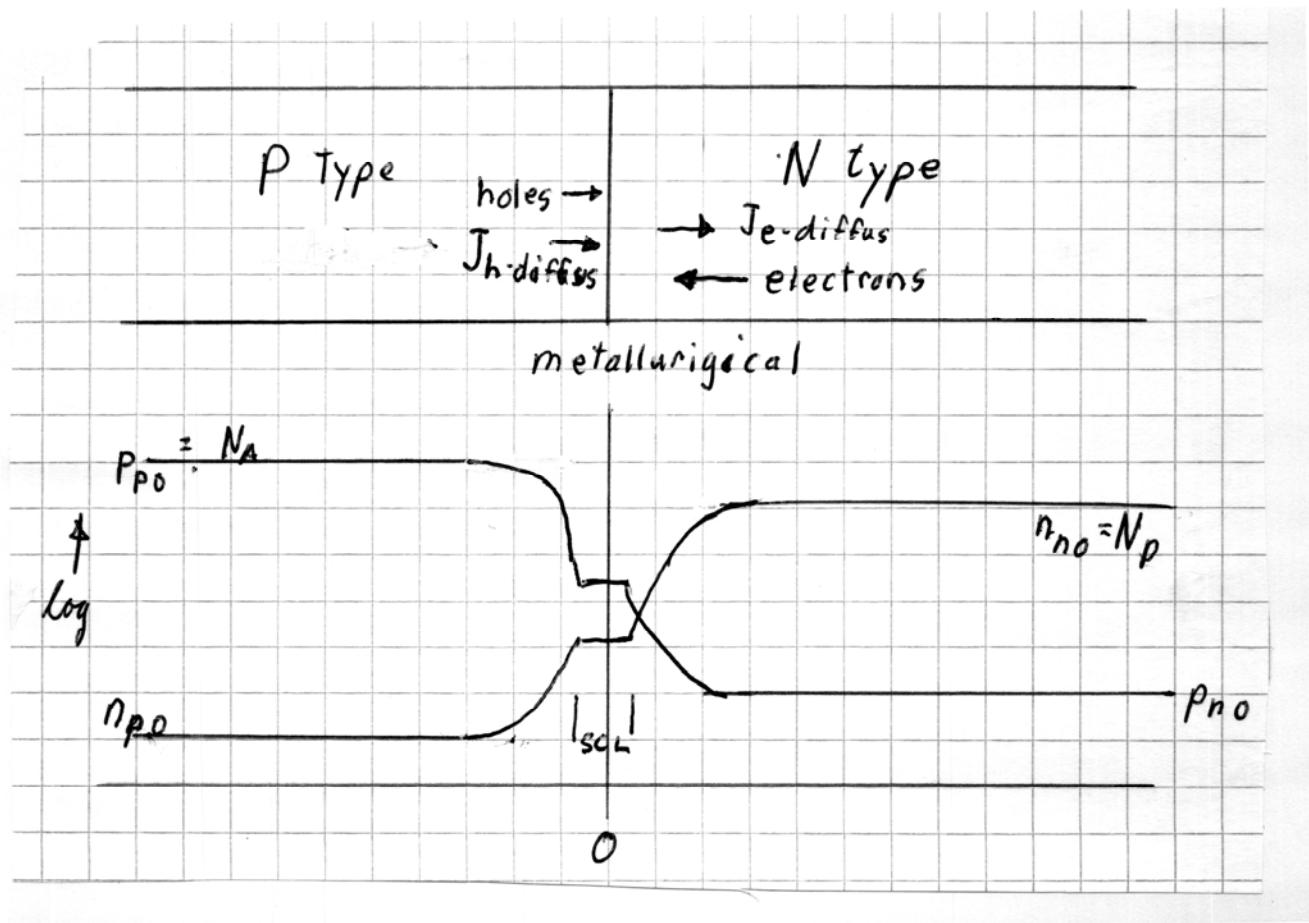


The PN Junction Diode

- PN junction diode is the basis of all semiconductor devices.
- Consider a block of P doped semiconductor,
- Attach it to block of N type,
- Forms an "abrupt" or "metallurgical" junction.
- Diffusion of electrons from N side, holes from P side Majority Carriers diffuse into minority region
- This sets up an electric field within the junction
- Result is a one directional, diode like I/V curve
- How is this obtained?



Photolithography method

- Grow an glass (oxide) on wafer (heat silicon in steam or air)
- Use photolithography to define (pattern) an area
- Etch away glass to create opening
- Use diffusion or Ion Implantation to create junction

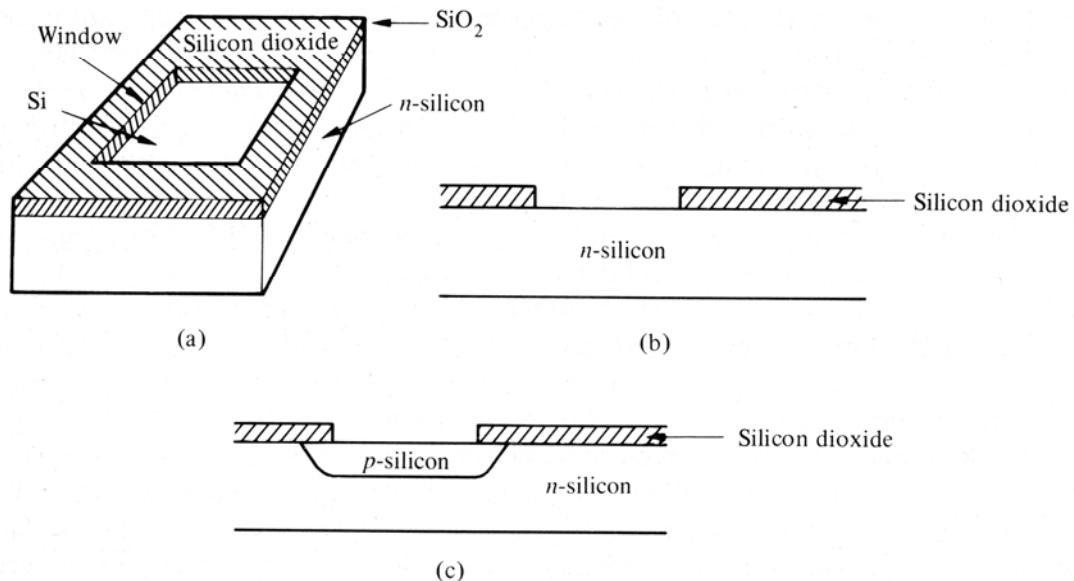


Fig. 1.2 (a) Window in SiO₂; (b) cross section before diffusion; (c) cross section after p-impurity diffusion.

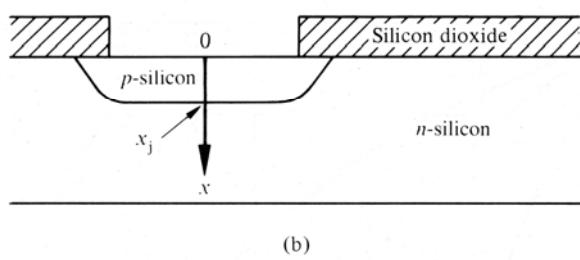


Fig. 1.3 (b) x-coordinate axis for impurities.

Potential Energy and Band Bending

- Energy band diagrams show change in E with position
- Electric fields in some areas may "bend" the bands
- Potential Energy (PE) shown by this relative to reference energy E_{ref}
- Change in particle position changes PE to Kinetic Energy

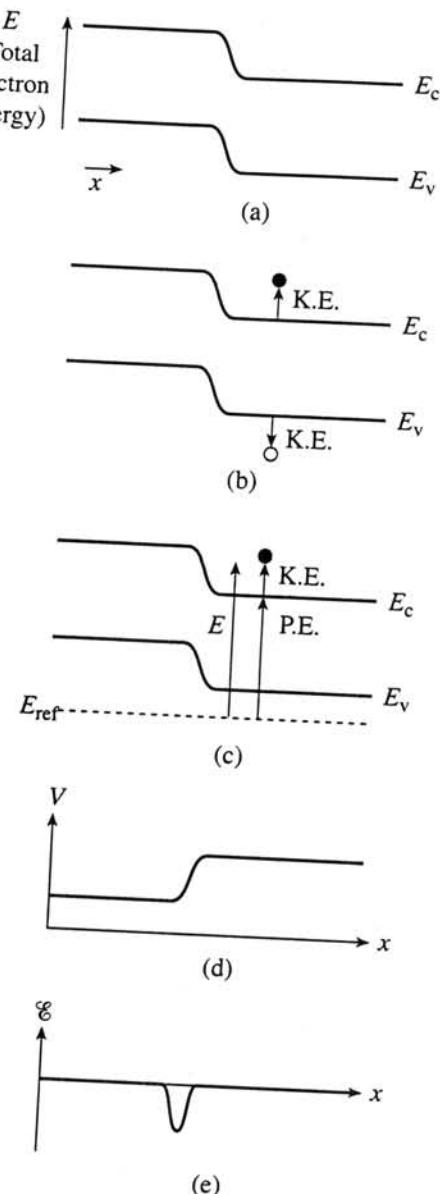


Figure 3.10 Relationship between band bending and the electrostatic variables inside a semiconductor: (a) sample energy band diagram exhibiting band bending; (b) identification of the carrier kinetic energies; (c) specification of the electron potential energy; (d) electrostatic potential and band diagram.

PE and Voltages

- Related PE to the electrostatic potential (V) by

$$PE = -qV = E_c - E_{ref}$$

$$V = -\frac{(E_c - E_{ref})}{q}$$

- Definition V related to the Electric field by the gradient

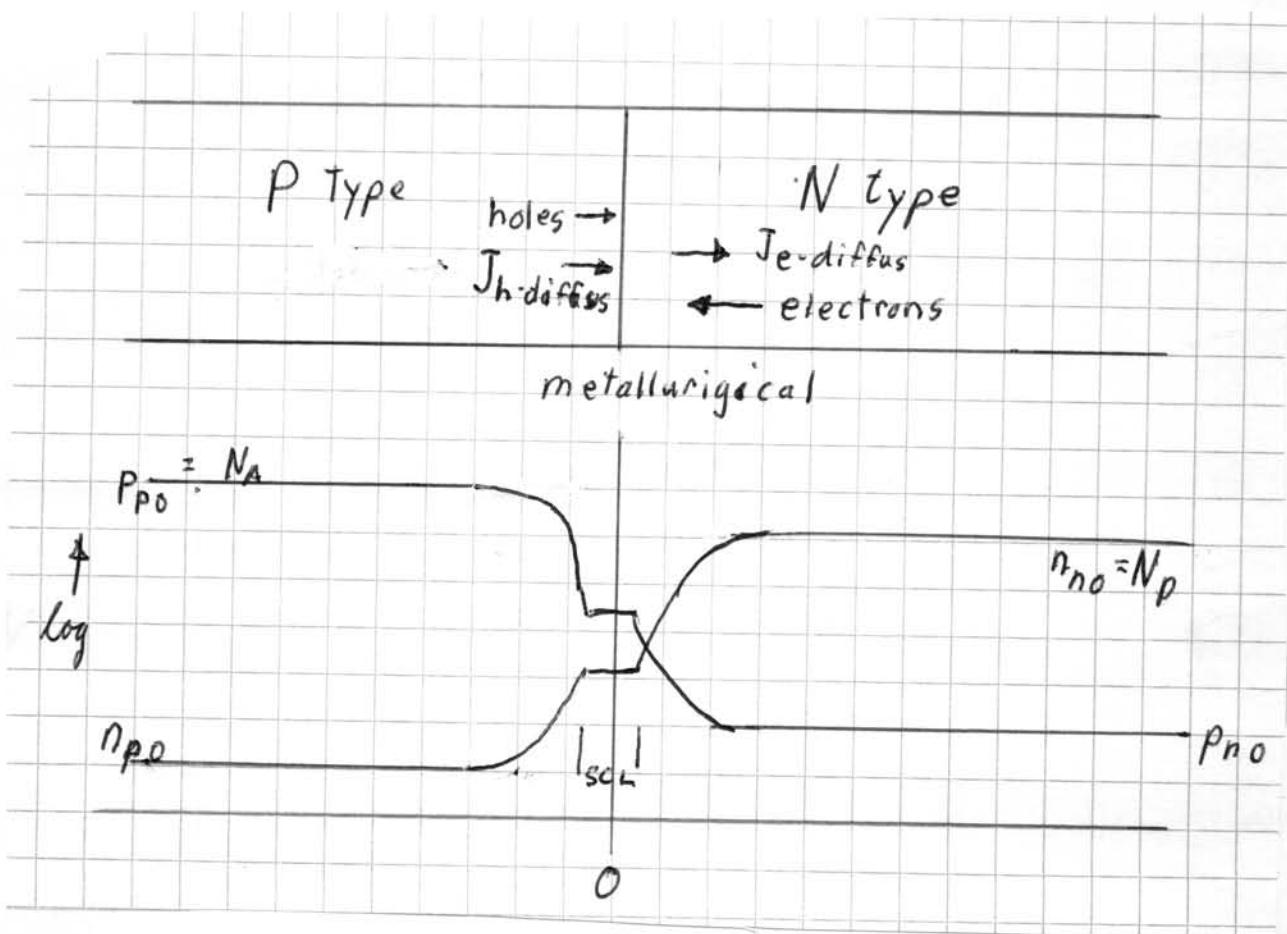
$$\vec{E} = -\nabla V$$

- Thus

$$\vec{E} = \frac{1}{q} \frac{dE_c}{dx}$$

PN Junction Diode

- For an abrupt junction
- (a) initially diffusion forces: cause holes near junction to diffuse from the P material to the N type,
- while electrons diffuse from the N type to the P.
- depletes the carriers in junction area,
- called the "depletion region" or the "Space Charge Layer"
- (b) injected excess minority carriers from the diffusion current (hole in the N type, electrons in the P type)
- minority carrier decays due to the recombination lifetime
- (c) diffusion leaves neg ion cores in P type near junction, positive ion cores in the N type.
- ions create an E field which balances out the diffusion forces.
- E field is a reflection of the difference in the Fermi Energy levels between the P and N.



E field in the PN junction

- Build up of charge can be related to E field by

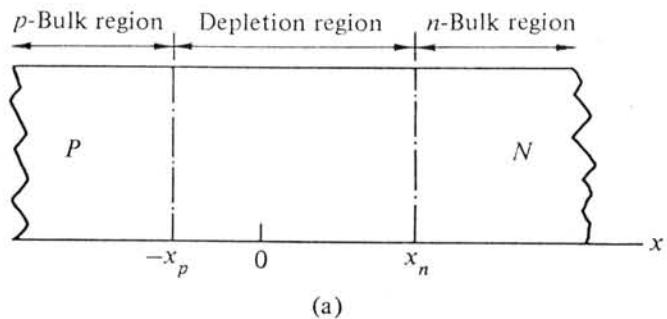
$$\vec{E} = \frac{1}{\epsilon_r \epsilon_0} \int_{-\infty}^x \rho(x) dx \text{ V/m}$$

- where ϵ_0 = permittivity of free space = 8.854×10^{-14}
- ϵ_r is the relative dielectric constant
 - $\epsilon_r = 11.9$ for silicon
 - (also called ϵ_s , K_s or K_r in some books) (book uses •)

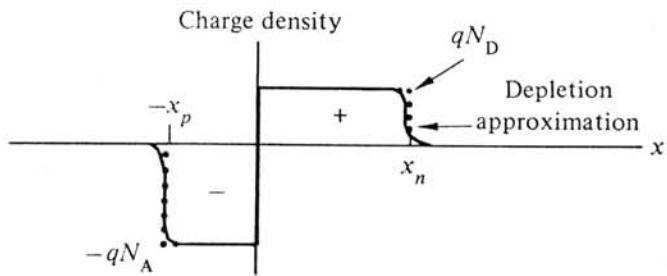
The total charge at any point is

$$\rho = q(p - n + N_D - N_A)$$

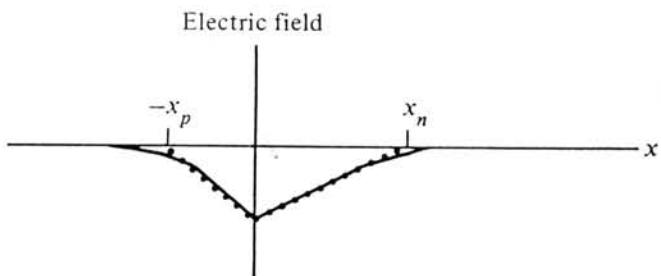
PN Charge Density, Carriers & E Field



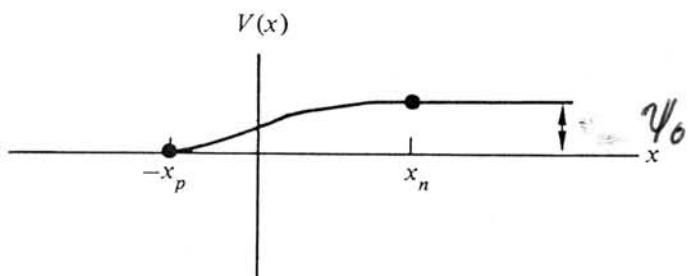
(a)



(b)



(c)



(d)

Fig. 2.5 Depletion approximation to the step junction.

The Unbiased diode

- difference in the doping levels generates a difference in the Fermi on the P and N region.

$$E_{FN} - E_i = k_B T \ln \left(\frac{n_n}{n_i} \right)$$

$$E_i - E_{FP} = k_B T \ln \left(\frac{p_p}{n_i} \right)$$

- unbiased condition Fermi energy must be at same potential throughout the device,
- thus the potential energy levels must change so that the E_{FN} matches the E_{FP} .
- This creates a potential energy barrier called:

$$\psi_0 = \frac{E_{FN} - E_{FP}}{q} = \frac{k_B T}{q} \ln \left(\frac{N_D N_A}{n_i^2} \right)$$

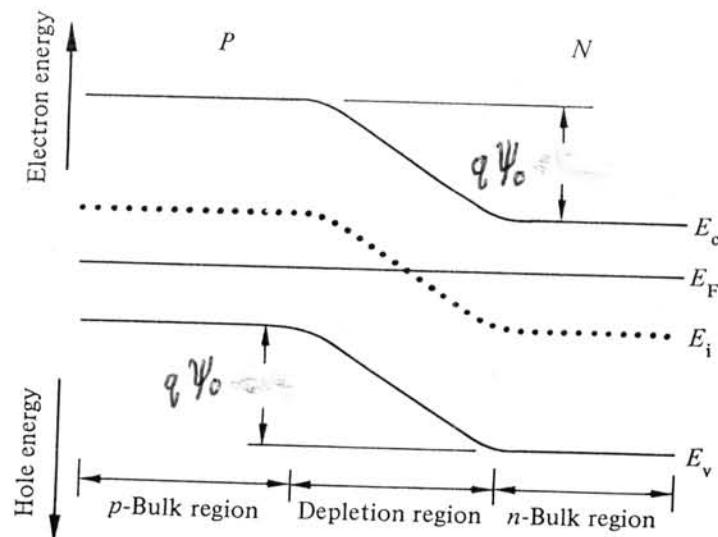


Fig. 2.4 A $p-n$ junction energy band diagram at thermal equilibrium.

Built in Potential Barrier

- Since the minority holes in the N region are

$$p_n = \frac{n_i^2}{N_D}$$

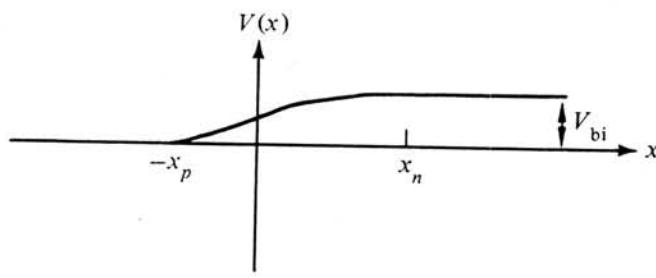
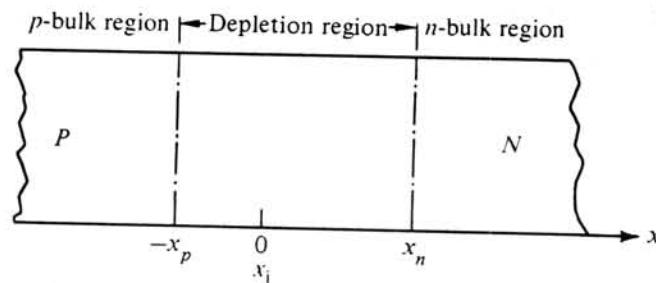
- this gives the "Boltzmann relationship"

$$\psi_0 = \frac{k_B T}{q} \ln \left(\frac{p_{p0}}{p_{n0}} \right)$$

- Similarly for the electrons

$$\psi_0 = \frac{k_B T}{q} \ln \left(\frac{n_{n0}}{n_{p0}} \right)$$

- where the zero subscript on carriers represents the densities well away from the junction.
- Note: book uses V_{bi} for potential; most others use Ψ_0
- This built in potential creates a voltage barrier to the flow of current in the diode.



(d)

Fig. 2.3 Depletion region electrostatics.

Example of Potential Barrier

- Example: For $N_D = 10^{15}$ and $N_A = 10^{14}$
what is the potential barrier height at 300 K in silicon

$$\psi_0 = 0.0259 \ln \left(\frac{10^{15} 10^{14}}{[1.5 \times 10^{10}]^2} \right) = 0.52 \text{ V}$$

- This represents the voltage barrier that must be overcome before the diode can be "turned on".
- Thus the Fermi energies appear as the fundamental characteristic of operation of the PN diode.

Depletion Approximation

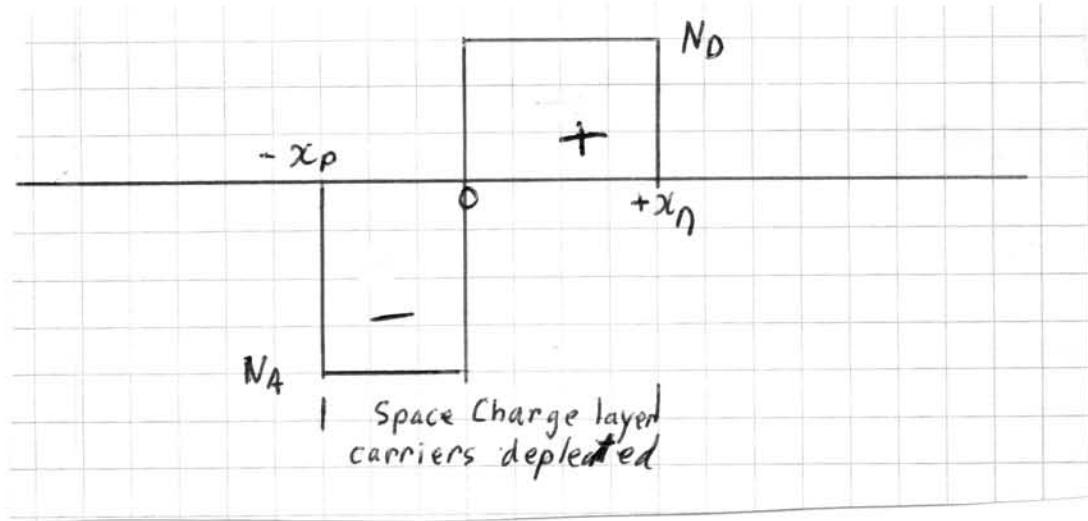
- diffusion of carriers sweeps the charges out of "Space Charge Layer" (SCL)
- making a depleted region.
- approximation is made that since there are few carriers there is no recombination in the Space Charge Layer.
- Thus only the ionic cores are present
- SCL extends from $-x_p$ to x_n
- Assume dopant level much greater than intrinsic level
- (a) Thus on P side

$$N_A > n_p \quad \rho = -qN_A \quad -x_p \leq x \leq 0$$

- (b) Thus on N side

$$N_D > p_n \quad \rho = qN_D \quad 0 \leq x \leq -x_n$$

- (c) Charge density is zero in bulk (outside SCL)



E field in the Space Charge Layer

- the requirement that net charge be the same on either side junctions requires:

$$qx_p N_A = qx_n N_D$$

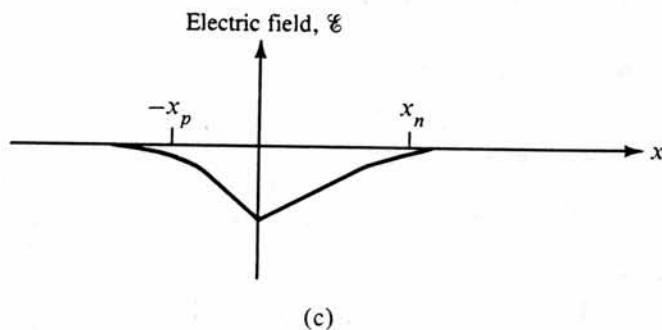
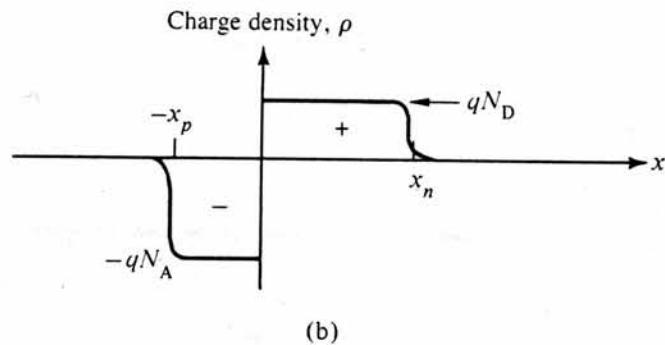
- Which reduces to the important depletion relationship

$$x_p N_A = x_n N_D$$

- E field created by charges can be thought of as the field between the two charged parallel plates of a capacitor
- then for the space charge layer the E field is linear:

$$E(x) = \frac{Q}{A\epsilon_r\epsilon_0} = \frac{qN_A}{\epsilon_r\epsilon_0}(x - x_p) = \frac{qN_D}{\epsilon_r\epsilon_0}(x + x_n)$$

- where A = the area of the junction
 ϵ_0 = permittivity of free space = 8.85×10^{-14} F/cm
 ϵ_r is the relative dielectric constant



Width of E field in the Space Charge Layer

- For points within the space charge layer since the potential (voltage) across the junction is given by

$$\Psi_0 = \int_{-x_p}^0 E(x) dx + \int_0^{x_n} E(x) dx$$

- Since

$$E(x) = \frac{qN_A}{\epsilon_r \epsilon_0} (x - x_p) = \frac{qN_D}{\epsilon_r \epsilon_0} (x + x_n)$$

- Hence

$$\Psi_0 = \frac{qN_A x_p^2}{2\epsilon_r \epsilon_0} + \frac{qN_D x_n^2}{2\epsilon_r \epsilon_0}$$

- Substituting in the charge balance

$$x_p = x_n \frac{N_D}{N_A}$$

$$\Psi_0 = \frac{qN_D^2 x_n^2}{2\epsilon_r \epsilon_0 N_A} + \frac{qN_D x_n^2}{2\epsilon_r \epsilon_0}$$

- Solving for the N side width

$$x_n = \left[\frac{2\epsilon_r \epsilon_0 \Psi_0}{q} \left(\frac{N_A}{N_D(N_A + N_D)} \right) \right]^{\frac{1}{2}}$$

Width of the Space Charge Layer

- Solving for the P side width by substitution

$$x_n = \left[\frac{2\epsilon_r \epsilon_0 \psi_0}{q} \left(\frac{N_D}{N_A(N_A + N_D)} \right) \right]^{\frac{1}{2}}$$

- Then let the width of the space charge layer be W_{scl}

$$W_{scl} = x_p + x_n$$

and solve for

$$W_{scl} = x_p + x_n = \left[\frac{2\epsilon_r \epsilon_0 \psi_0}{q} \left(\frac{N_A + N_D}{N_A N_D} \right) \right]^{\frac{1}{2}}$$

- Note the charges separated by a distance creates an effective capacitance
- C varies with the dopant level and junction width.

Example Width of Space Charge Layer

- Example: for $N_A = 10^{15}$ and $N_D = 10^{14} \text{ cm}^{-3}$
- then find the width of the space charge layer.
- As before

$$\psi_0 = 0.0259 \ln \left(\frac{10^{15} 10^{14}}{[1.5 \times 10^{10}]^2} \right) = 0.52 \text{ V}$$

- Then the widths are

$$x_n = \left[\frac{2 \varepsilon_r \varepsilon_0 \psi_0}{q} \left(\frac{N_D}{N_A (N_A + N_D)} \right) \right]^{\frac{1}{2}}$$

$$x_n = \left[\frac{2 \times 11.8 \times 8.85 \times 10^{-14} \times 0.52}{1.6 \times 10^{-19}} \left\{ \frac{10^{15}}{10^{14} (10^{15} + 10^{14})} \right\} \right]^{\frac{1}{2}} = 2.5 \times 10^{-4} \text{ cm}$$

$$x_n = 2.5 \text{ microns}$$

$$x_p = x_n \frac{N_D}{N_A} = 2.5 \times 10^{-4} \frac{10^{14}}{10^{15}} 0.25 \text{ microns}$$

$$W_{scl} = \left[\frac{2 \times 11.8 \times 8.85 \times 10^{-14} \times 0.52}{1.6 \times 10^{-19}} \left\{ \frac{10^{15} + 10^{14}}{10^{15} 10^{14}} \right\} \right]^{\frac{1}{2}} = 2.7 \times 10^{-4} \text{ cm}$$

$$W_{scl} = 2.7 \text{ microns}$$

Voltage within Space Charge Layer

- For points within the space charge layer, since the potential (voltage) across the junction is given by

$$\psi_0 = \int_{-x_p}^0 E dx + \int_0^{x_n} E dx = \frac{qN_A x_p^2}{2\epsilon_r \epsilon_0} + \frac{qN_D x_n^2}{2\epsilon_r \epsilon_0}$$

- Let the width of the space charge layer be W_{scl} . Since

$$x_p = \left[\frac{N_D}{N_A} \right] x_n$$

- Thus substituting into the potential equation gives

$$W_{scl} = x_p + x_n = x_n \left[1 + \frac{N_D}{N_A} \right] = \left[\frac{2\epsilon_r \epsilon_0 \psi_0}{q} \left(\frac{N_A + N_D}{N_A N_D} \right) \right]^{\frac{1}{2}}$$

- Note the existence of such charges separated by a distance creates an effective capacitance
- C varies with the dopant level and junction width.

Example of E field within the junction

- Example: for $N_A = 10^{15}$ and $N_D = 10^{14} \text{ cm}^{-3}$ then
 - (a) find the width of the space charge layer.
 - (b) calculate the electric field at the junction
- (a) As before

$$\psi_0 = 0.0259 \ln \left(\frac{10^{15} 10^{14}}{1.5 \times 10^{10}} \right) = 0.52 \text{ V}$$

$$W_{scl} = \left[\frac{11.8 \times 8.85 \times 10^{-14} \times 0.52}{1.6 \times 10^{-19}} \left\{ \frac{10^{15} + 10^{14}}{10^{15} 10^{14}} \right\} \right]^{\frac{1}{2}} = 2.73 \times 10^{-4} \text{ cm} = 2.7 \mu\text{m}$$

- (b) At the junction ($x = 0$) then

$$x_n = \frac{W_{scl}}{N_D} = \frac{2.73 \times 10^{-4}}{\left[1 + \frac{10^{14}}{10^{15}} \right]} = 2.48 \times 10^{-4} \text{ cm}$$

$$E(0) = \frac{q N_D}{\epsilon_r \epsilon_0} (x_n) = \frac{1.6 \times 10^{-19} \times 10^{14}}{1.05 \times 10^{-12}} \times 1.7 \times 10^{-4} = 3.79 \times 10^3 \text{ V/cm}$$

- The electric field is strong in the junction.

Currents in the unbiased PN diode

- There must be no current flowing without an applied voltage.
- Thus currents must balance in each region.
- The junction electric field creates a drift field of holes and electrons that exactly compensates the diffusion current.
- Thus in both regions:

$$J_{drift} = -J_{diff} \text{ but } J_{drift} \neq 0$$

- In the Energy diagram electrons in N type conduction band above P type conduction band have no barrier to overcome
- These can move across the depletion region.
- Holes in P type valance band below the N type valance band have no barrier to overcome
- move across the depletion region.
- These are the energy states that drift and diffuse across the barriers.

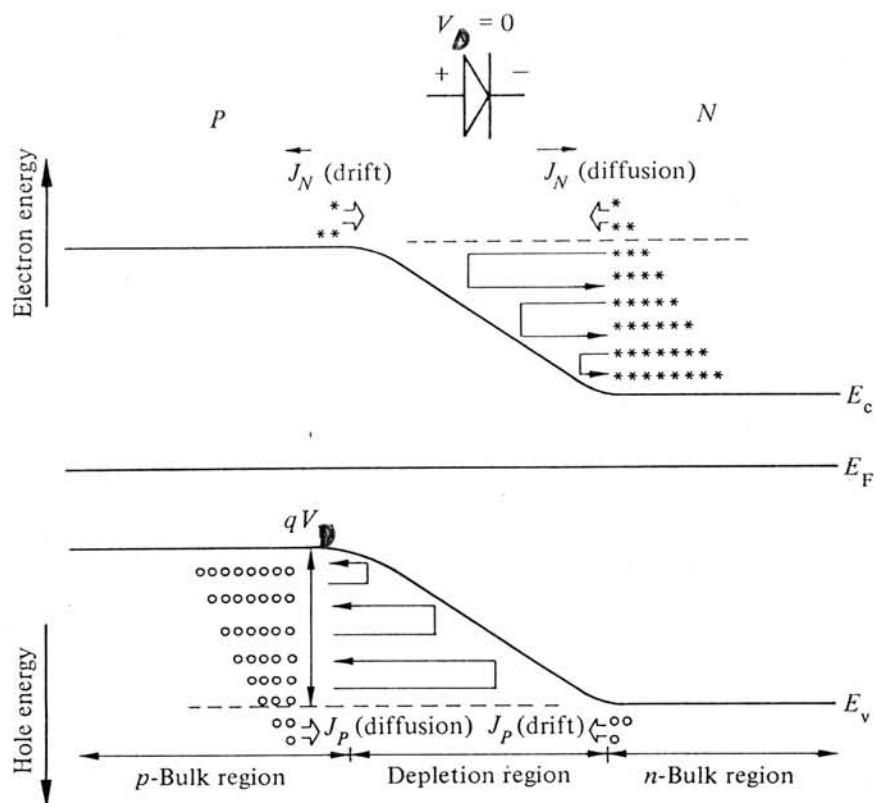


Fig. 3.1 Thermal equilibrium energy band diagram.

Applying bias to the PN junction

- When you apply a voltage V_A to the diode
- Voltage across Space Charge Layer different
- First there is contact potentials at metal contacts
- V_N on N side, V_P on P side
- When no voltage applied (no current flows)

$$\Psi = V_D = V_N + V_P$$

where V_D = applied junction voltage (Book uses V_j)

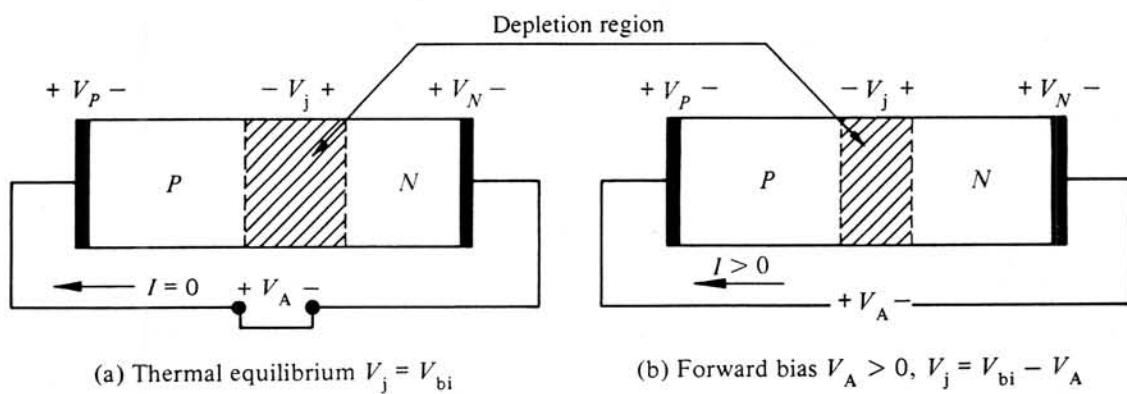


Fig. 2.6 Junction potential: (a) thermal equilibrium, $V_j = V_{bi}$; (b) forward bias $V_A > 0$, $V_j = V_{bi} - V_A$.

Applying bias to the PN junction

- If current flows there is resistive losses in diode as well

$$V_D = V_N + V_P - V_A + I(R_N + R_P)$$

- The effective potential at the junction is

$$\psi = \psi_0 - V_D$$

- As the diode is forward biased, the potential barrier shrinks
- as it is reversed biased the barrier grows larger.

Applied Bias and SCL Width in PN junction

- From the Poisson solution to the junction width
can just substitute the new potential into the junction
- the widths and potentials of the space charge layer to be:
- Thus on the p side

$$-x_p \leq x \leq 0$$

$$x_p = \left[\frac{2\epsilon_r \epsilon_0 (\psi_0 - V_D)}{q} \left(\frac{N_D}{N_A(N_A + N_D)} \right) \right]^{\frac{1}{2}}$$

$$V(x) = \frac{qN_A}{2\epsilon_r \epsilon_0} (x_p + x)^2$$

$$E(x) = -\frac{qN_A}{\epsilon_r \epsilon_0} (x + x_p)$$

Applied Bias and SCL Width in PN junction

- On the N side of the SCL

$$0 \leq x \leq x_n$$

$$x_n = \left[\frac{2\epsilon_r \epsilon_0 (p\psi_0 - V_D)}{q} \left(\frac{N_A}{N_D(N_A + N_D)} \right) \right]^{\frac{1}{2}}$$

$$V(x) = (\psi_0 - V_D) - \frac{qN_A}{2\epsilon_r \epsilon_0} (x_n - x)^2$$

$$E(x) = \frac{qN_D}{\epsilon_r \epsilon_0} (x_n - x)$$

- The combined SCL width changes as

$$W_{scl} = \left[\frac{2\epsilon_r \epsilon_0 (\psi_0 - V_D)}{q} \left(\frac{N_A + N_D}{N_A N_D} \right) \right]^{\frac{1}{2}}$$

- as forward bias applied: space charge layer becomes smaller,
- while as the reverse is applied it becomes larger.
- thus capacitance of diode changes with the applied bias, decreasing with reverse bias.

Real Changes in Junction width for applied Voltages

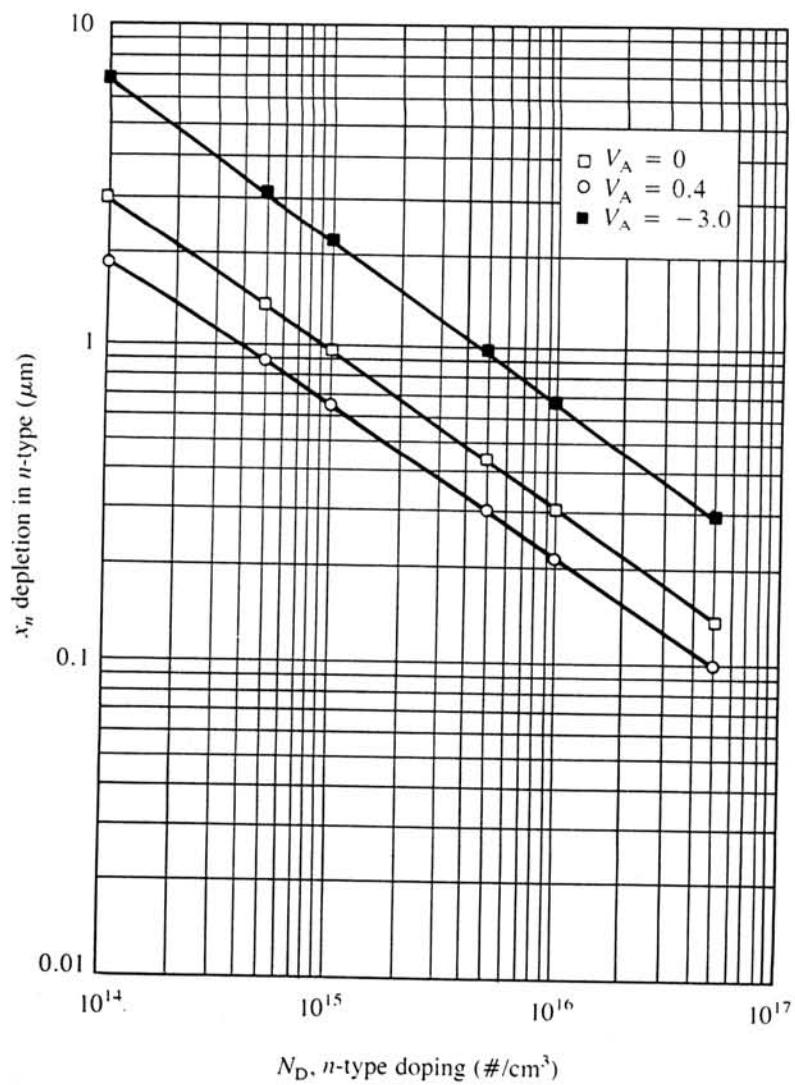
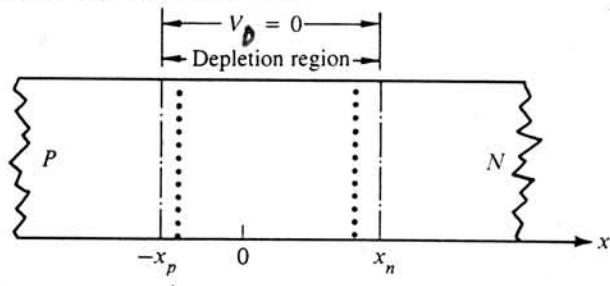


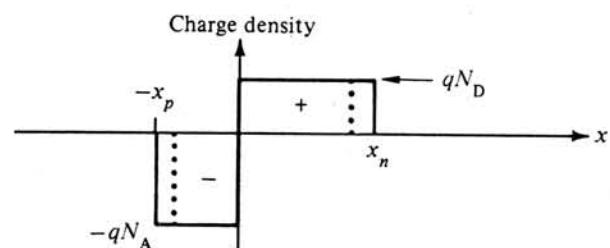
Fig. 2.9 n -depletion region for $V_A = 0$, 0.4, and -3.0 volts.

Forward Applied Bias and PN junction

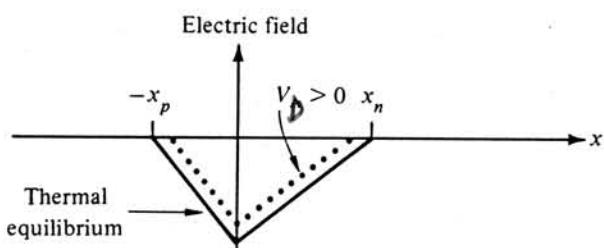
- When $V_D > 0$ and $V_D < \psi_0$
- SCL width is reduced on both sides
- E field is reduced by the added potential
- Potential barrier height is reduced
- Thus easier for carriers to move across



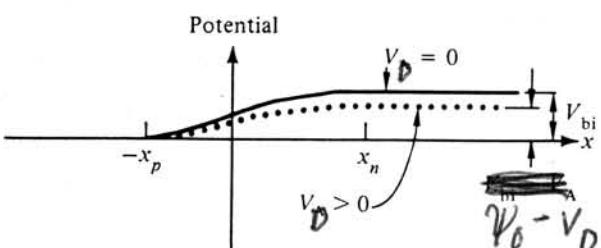
(a)



(b)



(c)

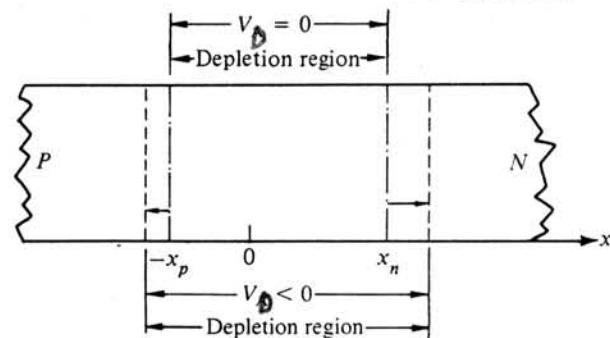


(d)

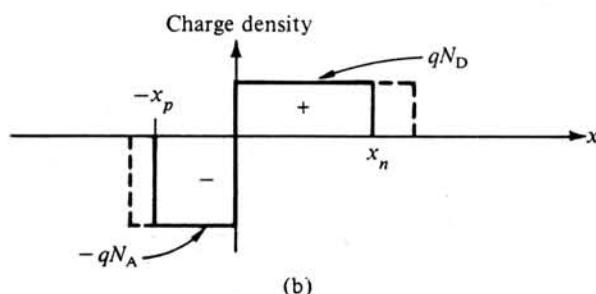
Fig. 2.7 Effect of forward bias on the diode electrostatics ($V_D > 0$, dotted lines; $V_D = 0$, unbroken lines).

Reverse Applied Bias and PN junction

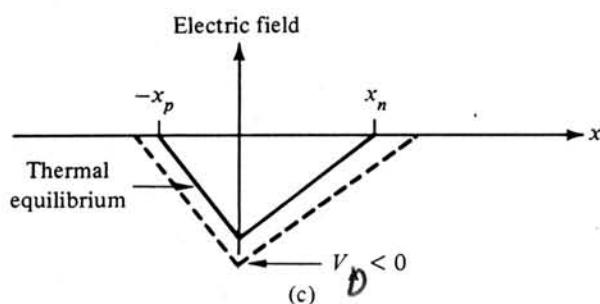
- When $V_D < 0$
- SCL width is increased on both sides
- E field is increased by the added potential
- Potential barrier height is heightened
- Thus harder for carriers to move across



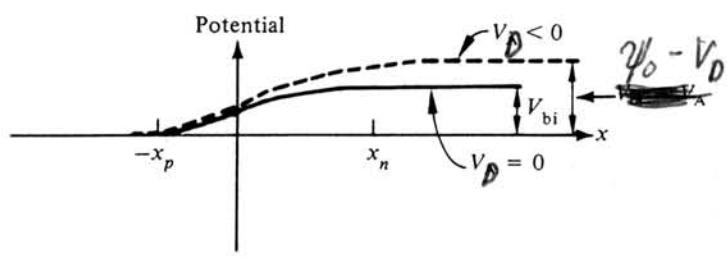
(a)



(b)



(c)



(d)

Fig. 2.8 Effect of bias on depletion region electrostatics ($V_D < 0$, dashed lines; $V_D = 0$, unbroken lines).

Applied Bias and PN junction

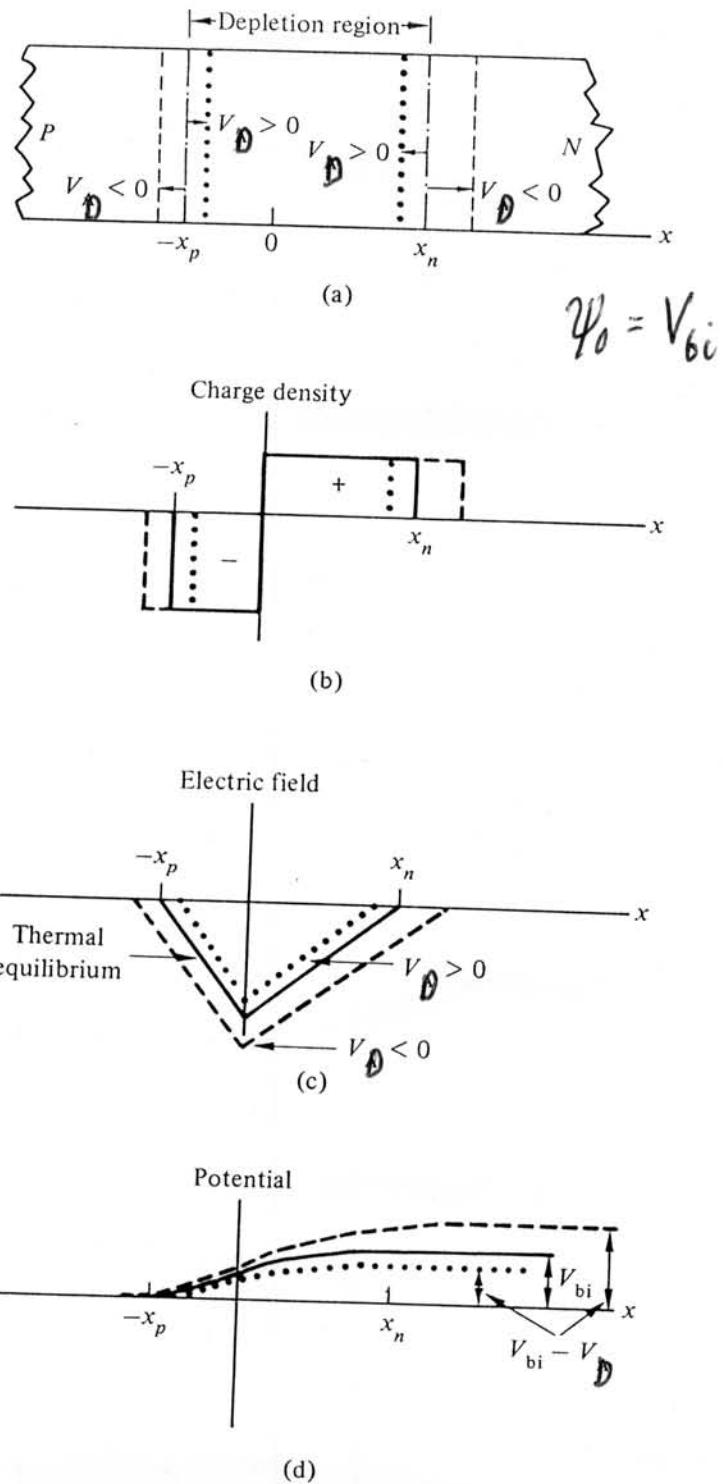
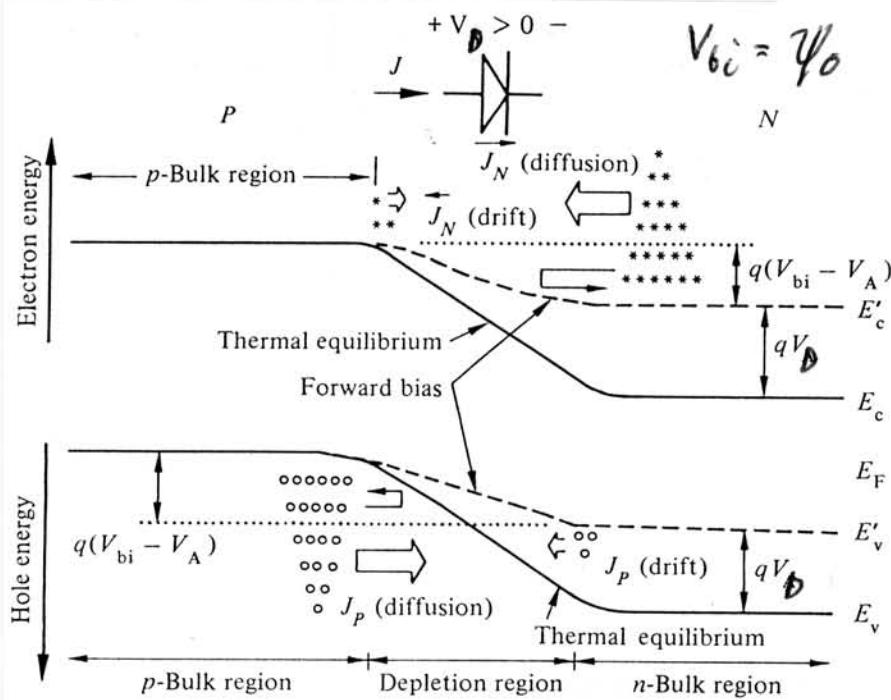


Fig. 2.8 Effect of bias on depletion region electrostatics.

Applied Bias PN Energy Diagrams

10



$$J = J_p + J_n$$

Fig. 3.3 Energy band diagram for forward bias and at thermal equilibrium.

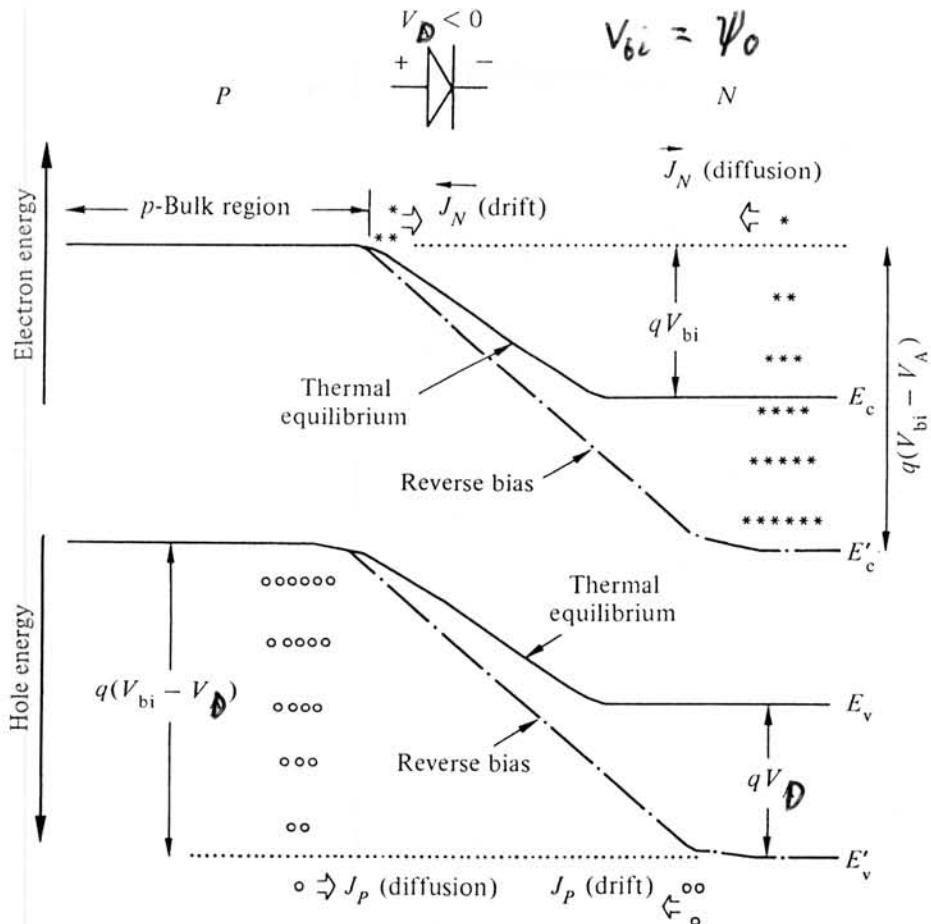
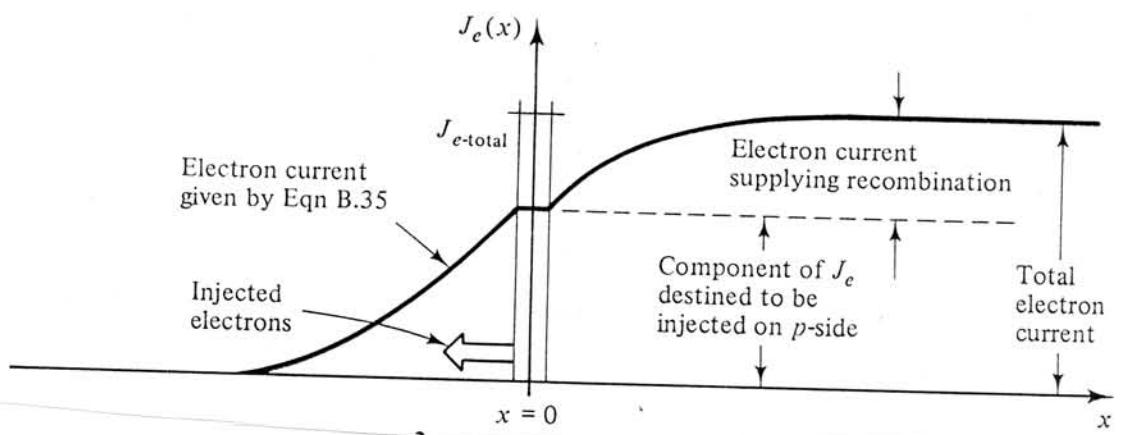
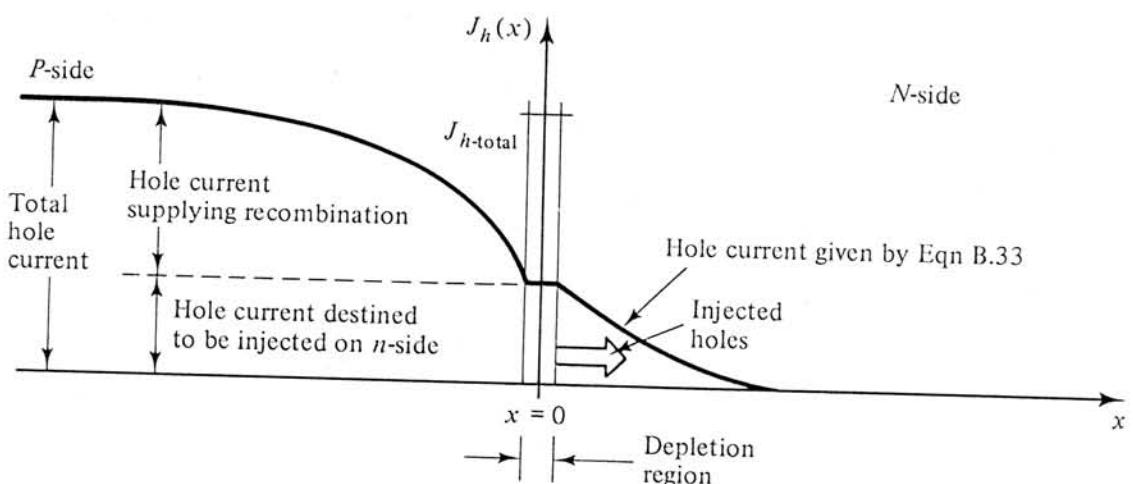


Fig. 3.4 Energy band diagram for reverse bias and at thermal equilibrium.

Applying Forward bias to the PN junction

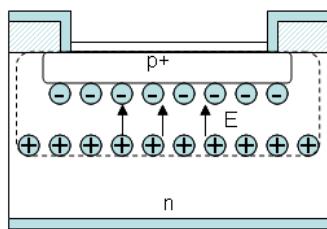
- apply a voltage to the diode: drift current increases
- more holes are carried from P region into the N region,
- where they become minority carriers
- similarly electrons go from major carriers in N region to minority carriers in the P region.
- Thus you are injecting minority carrier into each region.

Figure B.6
Hole and electron current density components in the forward-biased PN junction of Fig. B.4. The total current density is uniform at any position x .

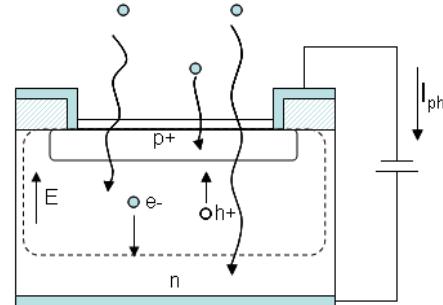


Photodiode and light

- Any large diode is a photodiode
- Light creates electron hole pairs as it is absorbed
- The E field at junction separates the charges
- Holes (p) go in direction of E field
- e's (n) opposite E field
- Result is charge builds up on the junction



(a) unbiased



(b) reverse biased

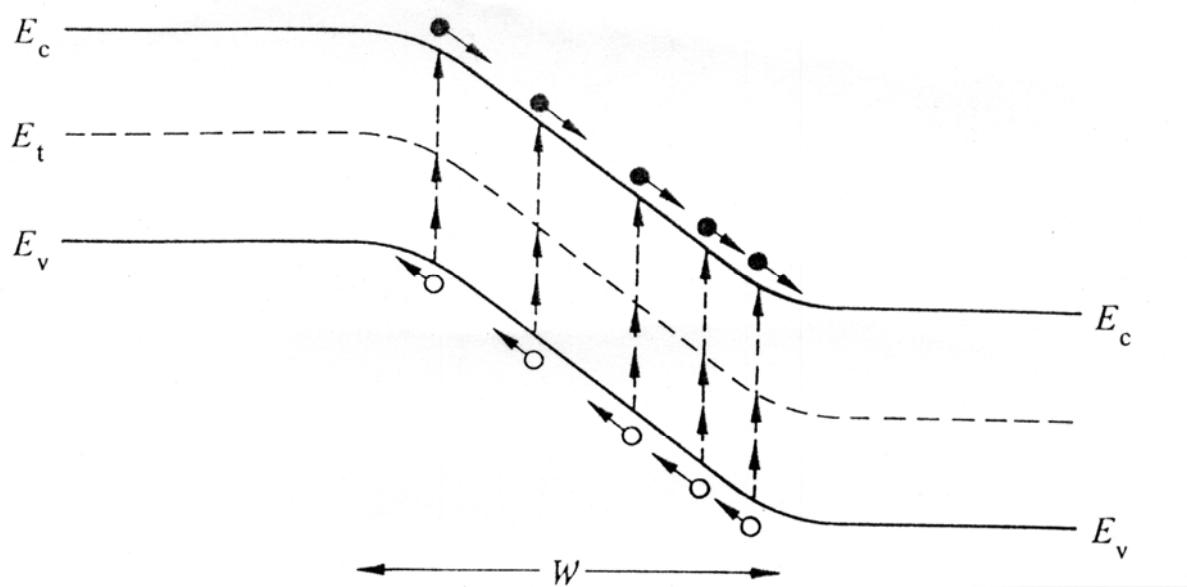
Generation and the Reverse Current

- Previously assumed no generation in the Space Charge Layer
- Within space charge layer the temperature electron-hole pairs
- When reverse biased diode very few carriers in the junction,
- Thus carriers generated within the junction dominate.
- Generated carriers swept out of junction by the electric field
- Holes pulled to the N side and electrons to the P
- There recombine with the majority carriers
- Create an additional current
- Called the "Recombination/Generation current")
- Same recombination behaviour as in bulk
- Generation rate of these carriers is given by:

$$G = \frac{n_i}{2\tau_0}$$

- τ_0 is the effective lifetime
- Average of the electron and hole lifetimes.

$$\tau_0 = \frac{\tau_n + \tau_p}{2}$$



Total Recombination/Generated Current in Junction

- Thus total recombination/generated current in junction is
- Amount generated within the space charge layer
- Times the charge of the carriers q, and the junction area A:

$$I_{RG} = \frac{qAn_i}{2\tau} W_{scl}$$

- Recall as reverse bias is increased
- space charge layer width W_{scl} becomes larger
- Hence recombination/generation current becomes more important.

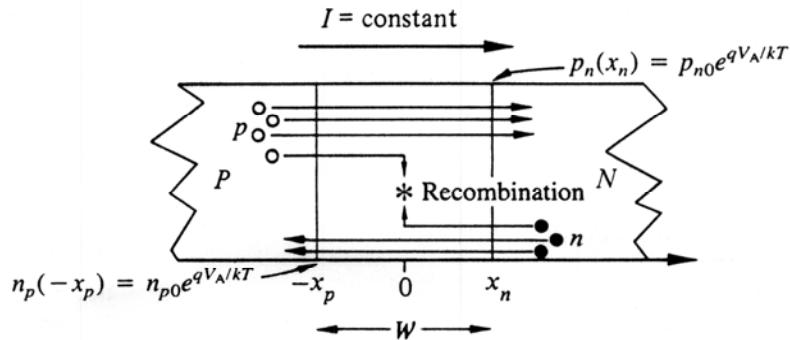


Fig. 4.8 Recombination as an additional current to the ideal diode in the depletion region under forward bias.

Diode Equation with RG

- Diode equation now becomes:

$$I = \left[I_s \exp\left(\frac{qV_D}{k_B T}\right) + I_{RG} \exp\left(\frac{qV_D}{2k_B T}\right) - 1 \right]$$

- Forward biased diode the I_{RG} term can often be neglected
- For silicon it is actually the dominate factor at room temperature
- Hence reverse leakage is much higher than expect
- Thus cannot measure reverse current and stick in diode equation
- Note as temperature drops closer to ideal

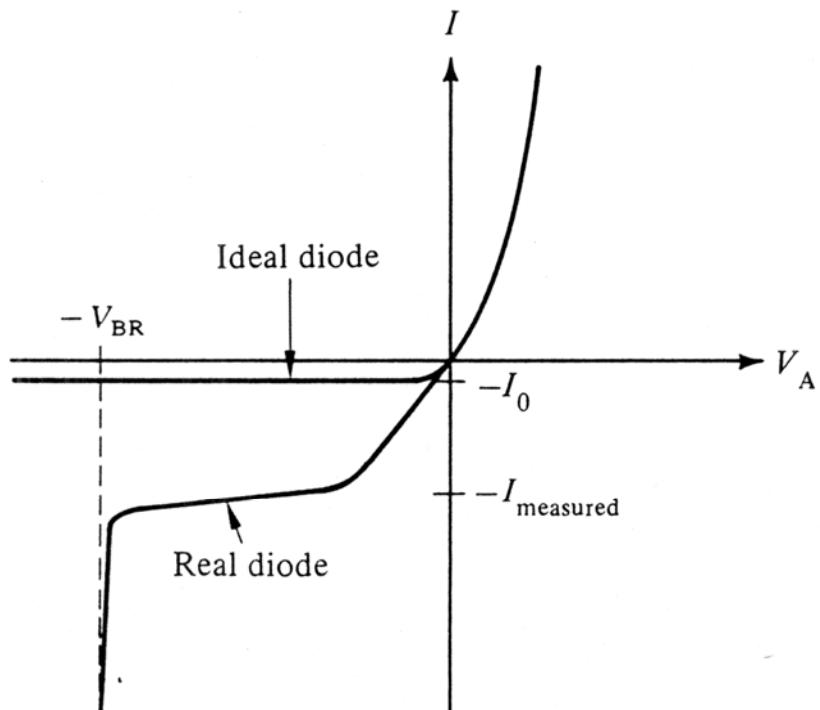


Fig. 4.1 Reverse-biased deviations from ideal.

Forward Bias Deviation from Ideal Diode Equation

In practice in silicon shows some modification from the ideal

$$I = I_s \left[\exp\left(\frac{qV_D}{\eta k_B T}\right) - 1 \right]$$

Where η is the ideality factor

Measure of how ideal the diode is

For modern silicon η ranges from 1.0 to 1.06 for 5 decades of I

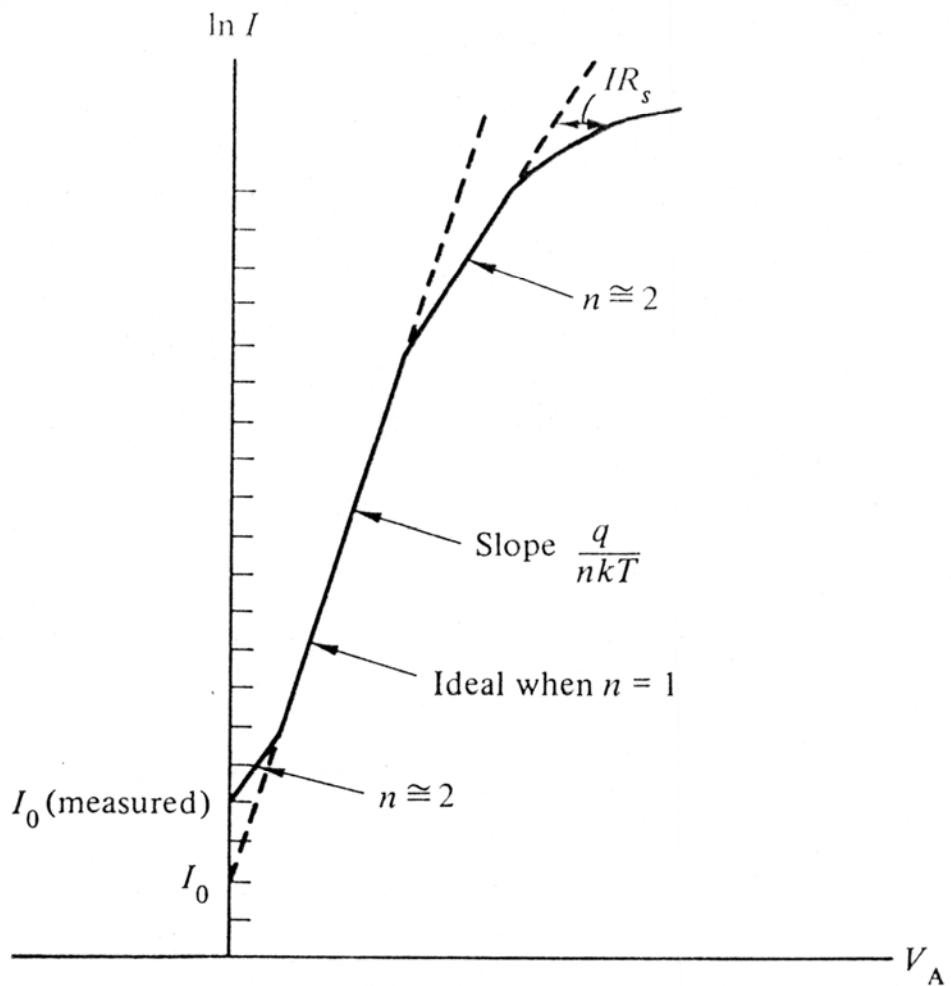


Fig. 4.7 Forward bias deviations from the ideal.